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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	M8C
Core Size	8-Bit
Speed	12MHz
Connectivity	I ² C, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	28
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy7c60323-ltxct

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Development Tools

PSoC Designer™ is the revolutionary integrated design environment (IDE) that you can use to customize PSoC to meet your specific application requirements. PSoC Designer software accelerates system design and time to market. Develop your applications using a library of precharacterized analog and digital peripherals (called user modules) in a drag-and-drop design environment. Then, customize your design by leveraging the dynamically generated application programming interface (API) libraries of code. Finally, debug and test your designs with the integrated debug environment, including in-circuit emulation and standard software debug features. PSoC Designer includes:

- Application editor graphical user interface (GUI) for device and user module configuration and dynamic reconfiguration
- Extensive user module catalog
- Integrated source-code editor (C and assembly)
- Free C compiler with no size restrictions or time limits
- Built-in debugger
- In-circuit emulation
- Built-in support for communication interfaces:
 - Hardware and software I²C slaves and masters
 - Full-speed USB 2.0
 - Up to four full-duplex universal asynchronous receiver/transmitters (UARTs), SPI master and slave, and wireless

PSoC Designer supports the entire library of PSoC 1 devices and runs on Windows XP, Windows Vista, and Windows 7.

PSoC Designer Software Subsystems

Design Entry

In the chip-level view, choose a base device to work with. Then select different onboard analog and digital components that use the PSoC blocks, which are called user modules. Examples of user modules are analog-to-digital converters (ADCs), digital-to-analog converters (DACs), amplifiers, and filters. Configure the user modules for your chosen application and connect them to each other and to the proper pins. Then generate your project. This prepopulates your project with APIs and libraries that you can use to program your application.

The tool also supports easy development of multiple configurations and dynamic reconfiguration. Dynamic reconfiguration makes it possible to change configurations at run time. In essence, this lets you to use more than 100 percent of PSoC's resources for an application.

Code Generation Tools

The code generation tools work seamlessly within the PSoC Designer interface and have been tested with a full range of debugging tools. You can develop your design in C, assembly, or a combination of the two.

Assemblers. The assemblers allow you to merge assembly code seamlessly with C code. Link libraries automatically use absolute addressing or are compiled in relative mode, and linked with other software modules to get absolute addressing.

C Language Compilers. C language compilers are available that support the PSoC family of devices. The products allow you to create complete C programs for the PSoC family devices. The optimizing C compilers provide all of the features of C, tailored to the PSoC architecture. They come complete with embedded libraries providing port and bus operations, standard keypad and display support, and extended math functionality.

Debugger

PSoC Designer has a debug environment that provides hardware in-circuit emulation, allowing you to test the program in a physical system while providing an internal view of the PSoC device. Debugger commands allow you to read and program and read and write data memory, and read and write I/O registers. You can read and write CPU registers, set and clear breakpoints, and provide program run, halt, and step control. The debugger also lets you to create a trace buffer of registers and memory locations of interest.

Online Help System

The online help system displays online, context-sensitive help. Designed for procedural and quick reference, each functional subsystem has its own context-sensitive help. This system also provides tutorials and links to FAQs and an Online Support Forum to aid the designer.

In-Circuit Emulator

A low-cost, high-functionality in-circuit emulator (ICE) is available for development support. This hardware can program single devices.

The emulator consists of a base unit that connects to the PC using a USB port. The base unit is universal and operates with all PSoC devices. Emulation pods for each device family are available separately. The emulation pod takes the place of the PSoC device in the target board and performs full-speed (24 MHz) operation.

Designing with PSoC Designer

The development process for the PSoC device differs from that of a traditional fixed-function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and lowering inventory costs. These configurable resources, called PSoC blocks, have the ability to implement a wide variety of user-selectable functions. The PSoC development process is:

1. Select [user modules](#).
2. Configure user modules.
3. Organize and connect.
4. Generate, verify, and debug.

Select User Modules

PSoC Designer provides a library of prebuilt, pretested hardware peripheral components called “user modules.” User modules make selecting and implementing peripheral devices, both analog and digital, simple.

Configure User Modules

Each user module that you select establishes the basic register settings that implement the selected function. They also provide parameters and properties that allow you to tailor their precise configuration to your particular application. For example, a PWM User Module configures one or more digital PSoC blocks, one for each eight bits of resolution. Using these parameters, you can establish the pulse width and duty cycle. Configure the parameters and properties to correspond to your chosen application. Enter values directly or by selecting values from drop-down menus. All of the user modules are documented in datasheets that may be viewed directly in PSoC Designer or on the Cypress website. These [user module datasheets](#) explain the internal operation of the user module and provide performance specifications. Each datasheet describes the use of each user module parameter, and other information that you may need to successfully implement your design.

Organize and Connect

Build signal chains at the chip level by interconnecting user modules to each other and the I/O pins. Perform the selection, configuration, and routing so that you have complete control over all on-chip resources.

Generate, Verify, and Debug

When you are ready to test the hardware configuration or move on to developing code for the project, perform the “Generate Configuration Files” step. This causes PSoC Designer to generate source code that automatically configures the device to your specification and provides the software for the system. The generated code provides APIs with high-level functions to control and respond to hardware events at run time, and interrupt service routines that you can adapt as needed.

A complete code development environment lets you to develop and customize your applications in C, assembly language, or both.

The last step in the development process takes place inside PSoC Designer's Debugger (accessed by clicking the Connect icon). PSoC Designer downloads the HEX image to the ICE where it runs at full-speed. PSoC Designer debugging capabilities rival those of systems costing many times more. In addition to traditional single-step, run-to-breakpoint, and watch-variable features, the debug interface provides a large trace buffer. It lets you to define complex breakpoint events that include monitoring address and data bus values, memory locations, and external signals.

Figure 6. CY7C60323-LTXC 32-pin Device Sawn

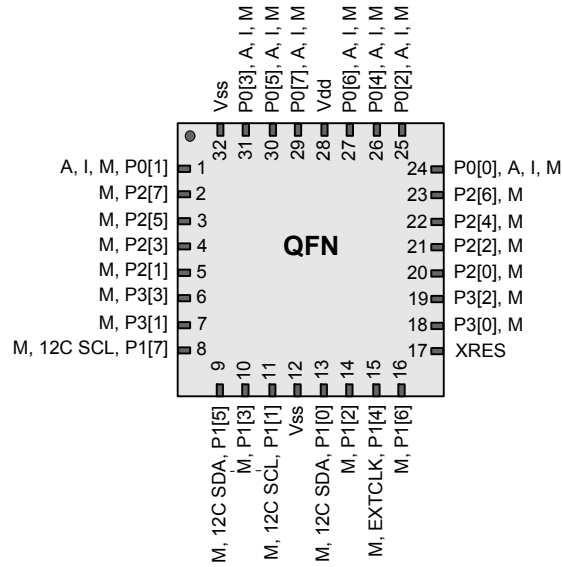


Figure 7. CY7C60333-LTXC 32-pin Device Sawn

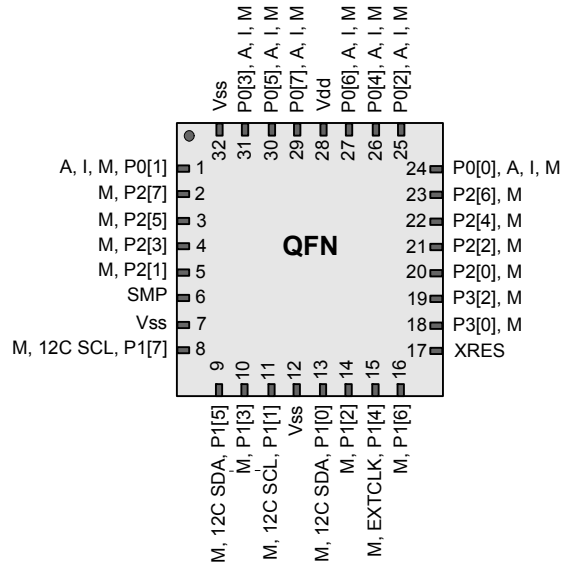


Table 3. 32-pin Part Pinout (QFN^[1])

Pin No.	Type		Name	Description
	Digital	Analog		
1	IO	I, M	P0[1]	Analog column mux input, integrating input.
2	IO	M	P2[7]	
3	IO	M	P2[5]	
4	IO	M	P2[3]	
5	IO	M	P2[1]	
6	IO	M	P3[3]	In CY7C60323 part.
6	Power		SMP	Switch mode pump (SMP) connection to required external components in CY7C60333 part.
7	IO	M	P3[1]	In CY7C60323 Part.
7	Power		Vss	Ground connection in CY7C60333 part.
8	IO	M	P1[7]	I ² C serial clock (SCL).
9	IO	M	P1[5]	I ² C serial data (SDA).
10	IO	M	P1[3]	
11	IO	M	P1[1]	I ² C SCL, ISSP-SCLK.
12	Power		Vss	Ground connection.
13	IO	M	P1[0]	I ² C SDA, ISSP-SDATA.
14	IO	M	P1[2]	
15	IO	M	P1[4]	Optional external clock input (EXTCLK).
16	IO	M	P1[6]	
17	Input		XRES	Active HIGH external reset with internal pull-down.
18	IO	M	P3[0]	
19	IO	M	P3[2]	
20	IO	M	P2[0]	
21	IO	M	P2[2]	
22	IO	M	P2[4]	
23	IO	M	P2[6]	
24	IO	I, M	P0[0]	Analog column mux input.
25	IO	I, M	P0[2]	Analog column mux input.
26	IO	I, M	P0[4]	Analog column mux input.
27	IO	I, M	P0[6]	Analog column mux input.
28	Power		V _{DD}	Supply voltage.
29	IO	I, M	P0[7]	Analog column mux input.
30	IO	I, M	P0[5]	Analog column mux input
31	IO	I, M	P0[3]	Analog column mux input, integrating input.
32	Power		Vss	Ground connection.

LEGEND A = analog, I = input, O = output, and M = analog mux input.

Note

1. The QFN package has a center pad that must be connected to ground (Vss).

Table 6. Register Map 1 Table: Configuration Space

Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access
PRT0DM0	00	RW		40		ASE10CR0	80	RW		C0	
PRT0DM1	01	RW		41			81			C1	
PRT0IC0	02	RW		42			82			C2	
PRT0IC1	03	RW		43			83			C3	
PRT1DM0	04	RW		44		ASE11CR0	84	RW		C4	
PRT1DM1	05	RW		45			85			C5	
PRT1IC0	06	RW		46			86			C6	
PRT1IC1	07	RW		47			87			C7	
PRT2DM0	08	RW		48			88			C8	
PRT2DM1	09	RW		49			89			C9	
PRT2IC0	0A	RW		4A			8A			CA	
PRT2IC1	0B	RW		4B			8B			CB	
PRT3DM0	0C	RW		4C			8C			CC	
PRT3DM1	0D	RW		4D			8D			CD	
PRT3IC0	0E	RW		4E			8E			CE	
PRT3IC1	0F	RW		4F			8F			CF	
	10			50			90		GDI_O_IN	D0	RW
	11			51			91		GDI_E_IN	D1	RW
	12			52			92		GDI_O_OU	D2	RW
	13			53			93		GDI_E_OU	D3	RW
	14			54			94			D4	
	15			55			95			D5	
	16			56			96			D6	
	17			57			97			D7	
	18			58			98		MUX_CR0	D8	RW
	19			59			99		MUX_CR1	D9	RW
	1A			5A			9A		MUX_CR2	DA	RW
	1B			5B			9B		MUX_CR3	DB	RW
	1C			5C			9C			DC	
	1D			5D			9D		OSC_GO_EN	DD	RW
	1E			5E			9E		OSC_CR4	DE	RW
	1F			5F			9F		OSC_CR3	DF	RW
DBB00FN	20	RW	CLK_CR0	60	RW		A0		OSC_CR0	E0	RW
DBB00IN	21	RW	CLK_CR1	61	RW		A1		OSC_CR1	E1	RW
DBB00OU	22	RW	ABF_CR0	62	RW		A2		OSC_CR2	E2	RW
	23		AMD_CR0	63	RW		A3		VLT_CR	E3	RW
DBB01FN	24	RW	CMP_GO_EN	64	RW		A4		VLT_CMP	E4	R
DBB01IN	25	RW		65			A5		ADC0_TR	E5	RW
DBB01OU	26	RW	AMD_CR1	66	RW		A6		ADC1_TR	E6	RW
	27		ALT_CR0	67	RW		A7			E7	
DCB02FN	28	RW		68			A8		IMO_TR	E8	W
DCB02IN	29	RW		69			A9		ILO_TR	E9	W
DCB02OU	2A	RW		6A			AA		BDG_TR	EA	RW
	2B		CLK_CR3	6B	RW		AB		ECO_TR	EB	W

Blank fields are Reserved and must not be accessed.

Access is bit specific.

Table 6. Register Map 1 Table: Configuration Space *(continued)*

Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access
DCB03FN	2C	RW	TMP_DR0	6C	RW		AC			EC	
DCB03IN	2D	RW	TMP_DR1	6D	RW		AD			ED	
DCB03OU	2E	RW	TMP_DR2	6E	RW		AE			EE	
	2F		TMP_DR3	6F	RW		AF			EF	
	30			70		RDI0RI	B0	RW		F0	
	31			71		RDI0SYN	B1	RW		F1	
	32		ACE00CR1	72	RW	RDI0IS	B2	RW		F2	
	33		ACE00CR2	73	RW	RDI0LT0	B3	RW		F3	
	34			74		RDI0LT1	B4	RW		F4	
	35			75		RDI0RO0	B5	RW		F5	
	36		ACE01CR1	76	RW	RDI0RO1	B6	RW		F6	
	37		ACE01CR2	77	RW		B7		CPU_F	F7	RL
	38			78			B8			F8	
	39			79			B9			F9	
	3A			7A			BA		FLS_PR1	FA	RW
	3B			7B			BB			FB	
	3C			7C			BC			FC	
	3D			7D			BD		DAC_CR	FD	RW
	3E			7E			BE		CPU_SCR1	FE	#
	3F			7F			BF		CPU_SCR0	FF	#

Blank fields are Reserved and must not be accessed.

Access is bit specific.

Absolute Maximum Ratings

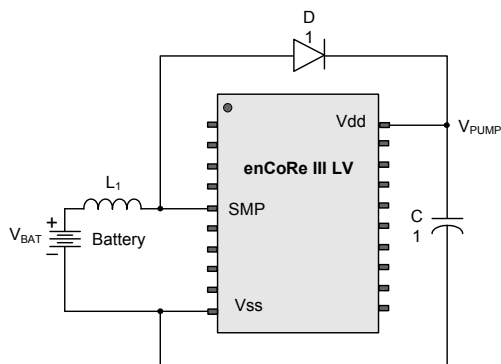
Table 7. Absolute Maximum Ratings

Parameter	Description	Min	Typ	Max	Unit	Notes
T _{STG}	Storage temperature	–40	–	+90	°C	Higher storage temperatures reduce data retention time.
T _{BAKETEMP}	Bake temperature		125	See package label	°C	
T _{BAKETIME}	Bake time	See package label		72	Hours	
T _A	Ambient temperature with power applied	0	–	+70	°C	
V _{DD}	Supply voltage on V _{DD} relative to V _{SS}	–0.5	–	5	V	
V _{IO}	DC input voltage	V _{SS} – 0.5	–	V _{DD} + 0.5	V	
V _{IOZ}	DC voltage applied to tri-state	V _{SS} – 0.5	–	V _{DD} + 0.5	V	
I _{MIO}	Maximum current into any port pin	–25	–	+25	mA	
ESD	Electro static discharge voltage	2000	–	–	V	Human body model ESD.
LU	Latch up current	–	–	200	mA	

Operating Temperature

Table 8. Operating Temperature

Parameter	Description	Min	Typ	Max	Unit	Notes
T _A	Ambient temperature	0	–	+70	°C	
T _J	Junction temperature	0	–	+85	°C	The temperature rise from ambient to junction is package specific. See Table 31 on page 30 . The user must limit the power consumption to comply with this requirement.

Figure 12. Basic Switch Mode Pump Circuit


DC Analog Mux Bus Specifications

Table 15 lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 3.0 V to 3.6 V and $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$, or 2.4 V to 3.0 V and $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$, respectively. Typical parameters apply to 3.3 V, or 2.7 V at 25°C and are for design guidance only.

Table 15. DC Analog Mux Bus Specifications

Parameter	Description	Min	Typ	Max	Unit	Notes
R_{SW}	Switch resistance to common analog bus	—	—	400 800	Ω Ω	$V_{\text{DD}} \geq 2.7\text{ V}$ $2.4\text{ V} \leq V_{\text{DD}} \leq 2.7\text{ V}$
R_{VDD}	Resistance of initialization switch to V_{DD}	—	—	800	Ω	

DC POR and LVD Specifications

Table 16 lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 3.0 V to 3.6 V and $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$, or 2.4 V to 3.0 V and $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$, respectively. Typical parameters apply to 3.3 V, or 2.7 V at 25°C and are for design guidance only.

Table 16. DC POR and LVD Specifications

Parameter	Description	Min	Typ	Max	Unit	Notes
V_{PPOR0}	V_{DD} value for PPOR Trip PORLEV[1:0] = 00b		2.36	2.40	V	V_{DD} must be greater than or equal to 2.5 V during startup, reset from the XRES pin, or reset from Watchdog.
V_{PPOR1}	PORLEV[1:0] = 01b	—	2.82	2.95	V	
V_{LVD0}	V_{DD} value for LVD Trip VM[2:0] = 000b	2.40	2.45	2.51 ^[3]	V	
V_{LVD1}	VM[2:0] = 001b	2.85	2.92	2.99 ^[4]	V	
V_{LVD2}	VM[2:0] = 010b	2.95	3.02	3.09	V	
V_{LVD37}	VM[2:0] = 011b	3.06	3.13	3.20	V	
V_{PUMP0}	V_{DD} value for PUMP Trip VM[2:0] = 000b	2.45	2.55	2.62 ^[5]	V	
V_{PUMP1}	VM[2:0] = 001b	2.96	3.02	3.09	V	
V_{PUMP2}	VM[2:0] = 010b	3.03	3.10	3.16	V	
V_{PUMP3}	VM[2:0] = 011b	3.18	3.25	3.32 ^[6]	V	

Notes

- Always greater than 50 mV above V_{PPOR} (PORLEV = 00) for falling supply.
- Always greater than 50 mV above V_{PPOR} (PORLEV = 01) for falling supply.
- Always greater than 50 mV above V_{LVD0} .
- Always greater than 50 mV above V_{LVD3} .

Table 20. 2.7 V AC Chip-Level Specifications

Parameter	Description	Min	Typ	Max	Unit	Notes
F _{IMO12}	Internal main oscillator (IMO) frequency for 12 MHz	11.5	12	12.7 ^[14, 15]	MHz	Trimmed for 2.7 V operation using factory trim values. See Figure 11 on page 15 . SLIMO mode = 1.
F _{IMO6}	IMO frequency for 6 MHz	5.5	6	6.5 ^[14, 15]	MHz	Trimmed for 2.7 V operation using factory trim values. See Figure 11 on page 15 . SLIMO mode = 1.
F _{CPU1}	CPU frequency (2.7 V nominal)	0.093	3	3.15 ^[14, 15]	MHz	12 MHz only for SLIMO mode = 0.
F _{BLK27}	Digital block frequency (2.7 V nominal)	0	12	12.5 ^[14, 15]	MHz	Refer to the AC digital block specifications.
F _{32K1}	Internal low speed oscillator frequency	8	32	96	kHz	
F _{32K_U}	Internal low speed oscillator untrimmed frequency	5	–	100	kHz	
DC _{ILO}	Internal low speed oscillator duty cycle	20	50	80	%	
T _{XRST}	External reset pulse width	10	–	–	μs	
F _{MAX}	Maximum frequency of signal on row input or row output.	–	–	12.3	MHz	
SR _{POWER_UP}	Power supply slew rate	–	–	250	V / ms	
T _{POWERUP}	Time from End of POR to CPU executing code	–	16	100	ms	
t _{jit_IMO}	12 MHz IMO cycle-to-cycle jitter (RMS) ^[16]	–	400	1000	ps	
	12 MHz IMO long term N cycle-to-cycle jitter (RMS) ^[16]	–	600	1300	ps	N = 32
	12 MHz IMO period jitter (RMS) ^[16]	–	100	500	ps	

Notes

 14. Accuracy derived from Internal Main Oscillator with appropriate trim for V_{DD} range.

 15. 2.4 V < V_{DD} < 3.0 V.

 16. Refer to Cypress Jitter Specifications Application Note [AN5054](#) "Understanding Datasheet Jitter Specifications for Cypress Timing Products" at www.cypress.com under Application Notes for more information.

AC Digital Block Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 3.0 V to 3.6 V and $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$, or 2.4 V to 3.0 V and $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$, respectively. Typical parameters apply to 3.3 V, or 2.7 V at 25°C and are for design guidance only.

Table 24. 3.3 V AC Digital Block Specifications

Function	Description	Min	Typ	Max	Unit	Notes
All Functions	Block input clock frequency	–	–	24.6	MHz	$3.0\text{ V} < V_{DD} < 3.6\text{ V}$.
Timer/ Counter/ PWM	Enable input pulse width	50 ^[17]	–	–	ns	
	Input clock frequency	–	–	24.6	MHz	
Dead Band	Kill pulse width:					
	Asynchronous restart mode	20	–	–	ns	
	Synchronous restart mode	50	–	–	ns	
	Disable mode	50	–	–	ns	
	Input clock frequency	–	–	24.6	MHz	$3.0\text{ V} \leq V_{DD} \leq 3.6\text{ V}$.
SPIM	Input clock frequency	–	–	8.2	MHz	The SPI serial clock (SCLK) frequency is equal to the input clock frequency divided by 2.
SPIS	Input clock frequency	–	–	4.1	MHz	Note for SPIS Input Clock Frequency: The input clock is the SPI SCLK in SPIS mode.
	Width of SS_ Negated between transmissions	50	–	–	ns	
Transmitter	Input clock frequency	–	–	24.6	MHz	The baud rate is equal to the input clock frequency divided by 8.
Receiver	Input clock frequency	–	–	24.6	MHz	The baud rate is equal to the input clock frequency divided by 8.

Table 25. 2.7 V AC Digital Block Specifications

Function	Description	Min	Typ	Max	Unit	Notes
All Functions	Block input clock frequency	–	–	12.7	MHz	$2.4\text{ V} \leq V_{DD} \leq 3.0\text{ V}$.
Timer/ Counter/ PWM	Enable input clock width	100	–	–	ns	
	Input clock frequency	–	–	12.7	MHz	
Dead Band	Kill pulse width:					
	Asynchronous restart mode	20	–	–	ns	
	Synchronous restart mode	100	–	–	ns	
	Disable mode	100	–	–	ns	
	Input clock frequency	–	–	12.7	MHz	$2.4\text{ V} \leq V_{DD} < 3.0\text{ V}$.
SPIM	Input clock frequency	–	–	6.35	MHz	The SPI serial clock (SCLK) frequency is equal to the input clock frequency divided by 2.
SPIS	Input clock frequency	–	–	4.1	MHz	Note for input clock frequency: The input clock is the SPI SCLK in SPIS mode.
	Width of SS_ Negated between transmissions	100	–	–	ns	
Transmitter	Input clock frequency	–	–	12.7	MHz	The baud rate is equal to the input clock frequency divided by 8.
Receiver	Input clock frequency	–	–	12.7	MHz	The baud rate is equal to the input clock frequency divided by 8.

Note

17. 50 ns minimum input pulse width is based on the input synchronizers running at 12 MHz (84 ns nominal period).

AC External Clock Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 3.0 V to 3.6 V and $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$, respectively. Typical parameters apply to 3.3 V, or 2.7 V at 25°C and are for design guidance only.

Table 26. 3.3 V AC External Clock Specifications

Parameter	Description	Min	Typ	Max	Unit	Notes
F _{OSCEXT}	Frequency with CPU clock divide by 1	0.093	–	12.3	MHz	Maximum CPU frequency is 12 MHz at 3.3 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.
F _{OSCEXT}	Frequency with CPU clock divide by 2 or greater	0.186	–	24.6	MHz	If the frequency of the external clock is greater than 12 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met.
–	High period with CPU clock divide by 1	41.7	–	5300	ns	
–	Low period with CPU clock divide by 1	41.7	–	–	ns	
–	Power-up IMO to switch	150	–	–	μs	

Table 27. 2.7 V AC External Clock Specifications

Parameter	Description	Min	Typ	Max	Unit	Notes
F _{OSCEXT}	Frequency with CPU clock divide by 1	0.093	–	3.08	MHz	Maximum CPU frequency is 3 MHz at 2.7 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.
F _{OSCEXT}	Frequency with CPU clock divide by 2 or greater	0.186	–	6.35	MHz	If the frequency of the external clock is greater than 3 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met.
–	High period with CPU clock divide by 1	160	–	5300	ns	
–	Low period with CPU clock divide by 1	160	–	–	ns	
–	Power-up IMO to switch	150	–	–	μs	

AC Programming Specifications

Table 28 lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 3.0 V to 3.6 V and $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$, respectively. Typical parameters apply to 3.3 V, or 2.7 V at 25°C and are for design guidance only.

Table 28. AC Programming Specifications

Parameter	Description	Min	Typ	Max	Unit	Notes
T _{RSCLK}	Rise time of SCLK	1	–	20	ns	
T _{FSCLK}	Fall time of SCLK	1	–	20	ns	
T _{SSCLK}	Data set up time to falling edge of SCLK	40	–	–	ns	
T _{HSCLK}	Data hold time from falling edge of SCLK	40	–	–	ns	
F _{SCLK}	Frequency of SCLK	0	–	8	MHz	
T _{ERASEB}	Flash erase time (Block)	–	10	–	ms	
T _{WRITE}	Flash block write time	–	40	–	ms	
T _{DSCLK3}	Data out delay from falling edge of SCLK	–	–	50	ns	$3.0 \leq V_{DD} \leq 3.6$
T _{DSCLK2}	Data out delay from falling edge of SCLK	–	–	70	ns	$2.4 \leq V_{DD} \leq 3.0$
T _{ERASEALL}	Flash erase time (Bulk)	–	20	–	ms	Erase all blocks and protection fields at once.
T _{PROGRAM_HOT}	Flash block erase + flash block write time	–	–	100	ms	$0^{\circ}\text{C} \leq T_J \leq 100^{\circ}\text{C}$
T _{PROGRAM_COLD}	Flash block erase + flash block write time	–	–	200	ms	$-40^{\circ}\text{C} \leq T_J \leq 0^{\circ}\text{C}$

AC I²C Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 3.0 V to 3.6 V and 0 °C ≤ T_A ≤ 70 °C, or 2.4 V to 3.0 V and 0 °C ≤ T_A ≤ 70 °C, respectively. Typical parameters apply to 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 29. AC Characteristics of the I²C SDA and SCL Pins for V_{DD} ≥ 3.0 V

Parameter	Description	Standard-Mode		Fast-Mode		Unit
		Min	Max	Min	Max	
F _{SCL I2C}	SCL clock frequency	0	100	0	400	kHz
T _{HDSTA I2C}	Hold time (repeated) START condition. After this period, the first clock pulse is generated.	4.0	—	0.6	—	μs
T _{LOW I2C}	LOW period of the SCL clock	4.7	—	1.3	—	μs
T _{HIGH I2C}	HIGH period of the SCL clock	4.0	—	0.6	—	μs
T _{SUSTA I2C}	Set up time for a repeated START condition	4.7	—	0.6	—	μs
T _{HDDAT I2C}	Data hold time	0	—	0	—	μs
T _{SUDAT I2C}	Data setup time	250	—	100 ^[18]	—	ns
T _{SUSTOI2C}	Set up time for STOP condition	4.0	—	0.6	—	μs
T _{BUFI2C}	Bus free time between a STOP and START condition	4.7	—	1.3	—	μs
T _{SPI2C}	Pulse width of spikes are suppressed by the input filter.	—	—	0	50	ns

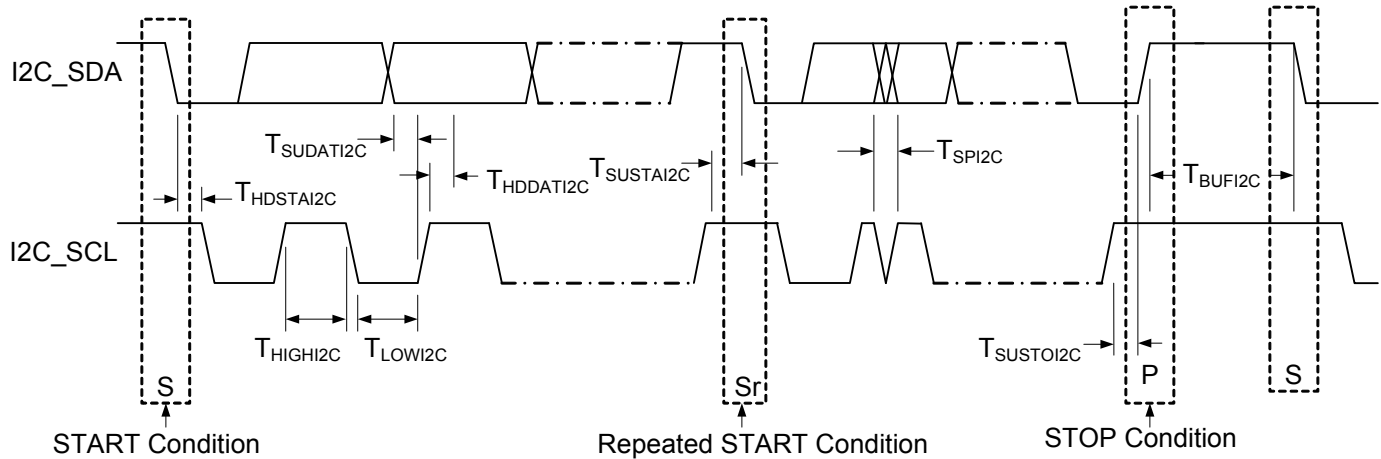
Table 30. 2.7 V AC Characteristics of the I²C SDA and SCL Pins (Fast-Mode not Supported)

Parameter	Description	Standard-Mode		Fast-Mode		Unit
		Min	Max	Min	Max	
F _{SCL I2C}	SCL clock frequency	0	100	—	—	kHz
T _{HDSTA I2C}	Hold time (repeated) START condition. After this period, the first clock pulse is generated.	4.0	—	—	—	μs
T _{LOW I2C}	LOW period of the SCL clock	4.7	—	—	—	μs
T _{HIGH I2C}	HIGH period of the SCL clock	4.0	—	—	—	μs
T _{SUSTA I2C}	Setup time for a repeated START condition	4.7	—	—	—	μs
T _{HDDAT I2C}	Data hold time	0	—	—	—	μs
T _{SUDAT I2C}	Data setup time	250	—	—	—	ns
T _{SUSTOI2C}	Setup Time for STOP Condition	4.0	—	—	—	μs
T _{BUFI2C}	Bus free time between a STOP and START condition	4.7	—	—	—	μs
T _{SPI2C}	Pulse width of spikes are suppressed by the input filter.	—	—	—	—	ns

Note

18. A fast-mode I²C-bus device can be used in a standard-mode I²C-bus system, but the requirement t_{SU;DAT} ≥ 250 ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line t_{rmax} + t_{SU;DAT} = 1000 + 250 = 1250 ns (according to the Standard-Mode I²C-bus specification) before the SCL line is released.

Figure 14. Definition of Timing for Fast-/Standard-Mode on the I²C Bus



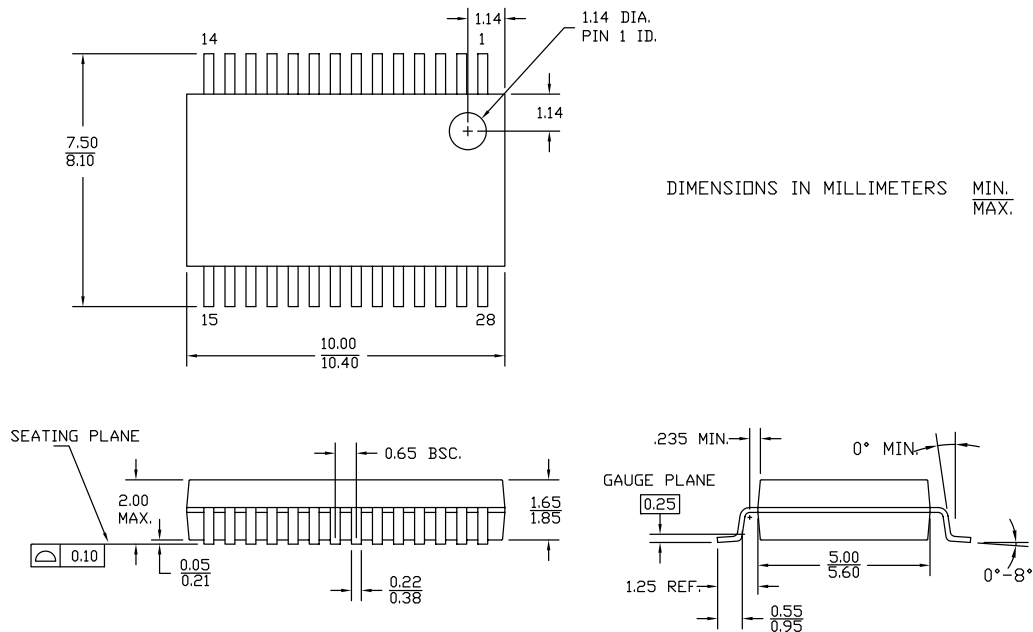
Packaging Information

This section illustrates the packaging specifications for the CY7C603xx device, along with the thermal impedances for each package.

Important Note Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the document titled PSoC Emulator Pod Dimensions at <http://www.cypress.com>.

Packaging Dimensions

Figure 15. 28-pin (210-Mil) SSOP



51-85079 *F

Acronyms

Acronyms Used

Table 34 lists the acronyms that are used in this document.

Table 34. Acronyms Used in this Datasheet

Acronym	Description	Acronym	Description
AC	alternating current	MIPS	million instructions per second
ADC	analog-to-digital converter	PCB	printed circuit board
API	application programming interface	PGA	programmable gain amplifier
CPU	central processing unit	PLL	phase-locked loop
CT	continuous time	POR	power-on reset
DAC	digital-to-analog converter	PPOR	precision power on reset
DC	direct current	PSoC®	Programmable System-on-Chip
DTMF	dual-tone multi-frequency	PWM	pulse-width modulator
ECO	external crystal oscillator	QFN	quad flat no leads
EEPROM	electrically erasable programmable read-only memory	RTC	real time clock
GPIO	general purpose I/O	SAR	successive approximation
ICE	in-circuit emulator	SC	switched capacitor
IDE	integrated development environment	SLIMO	slow IMO
ILO	internal low speed oscillator	SMP	switch mode pump
IMO	internal main oscillator	SPI™	serial peripheral interface
I/O	input/output	SRAM	static random access memory
ISSP	in-system serial programming	SROM	supervisory read only memory
LCD	liquid crystal display	SSOP	shrink small-outline package
LPC	low power comparator	USB	universal serial bus
LVD	low voltage detect	WDT	watchdog timer
MAC	multiply-accumulate	XRES	external reset

Reference Documents

CY8CPLC20, CY8CLED16P01, CY8C29x66, CY8C27x43, CY8C24x94, CY8C24x23, CY8C24x23A, CY8C22x13, CY8C21x34, CY8C21x23, CY7C64215, CY7C603xx, CY8CNP1xx, and CYWUSB6953 *PSoC® Programmable System-on-Chip Technical Reference Manual (TRM)* (001-14463)

Understanding Datasheet Jitter Specifications for Cypress Timing Products – [AN5054](#) (001-14503)

Application Notes for Surface Mount Assembly of Amkor's MicroLeadFrame (MLF) Packages – available at <http://www.amkor.com>.

Document Conventions

Units of Measure

Table 35 lists the units of measures.

Table 35. Units of Measure

Symbol	Unit of Measure	Symbol	Unit of Measure
kB	1024 bytes	μH	microhenry
dB	decibels	μs	microseconds
°C	degree Celsius	ms	milliseconds
μF	microfarads	ns	nanoseconds
fF	femtofarads	ps	picoseconds
pF	picofarads	μV	microvolts
kHz	kilohertz	mV	millivolts
MHz	megahertz	mVpp	millivolts peak-to-peak
rt-Hz	root hertz	nV	nanovolts
kΩ	kilohms	V	volts
Ω	ohm	μW	microwatts
μA	microamperes	W	watts
mA	milliamperes	mm	millimeter
nA	nanoamperes	ppm	parts per million
pA	picoamperes	%	percent

Numeric Conventions

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase 'h' (for example, '14h' or '3Ah'). Hexadecimal numbers may also be represented by a '0x' prefix, the C coding convention. Binary numbers have an appended lowercase 'b' (for example, '01010100b' or '01000011b'). Numbers not indicated by an 'h' or 'b' are decimals.

Glossary

active high	<ol style="list-style-type: none"> 1. A logic signal having its asserted state as the logic 1 state. 2. A logic signal having the logic 1 state as the higher voltage of the two states.
analog blocks	The basic programmable opamp circuits. These are switched capacitor (SC) and continuous time (CT) blocks. These blocks can be interconnected to provide ADCs, DACs, multi-pole filters, gain stages, and much more.
analog-to-digital (ADC)	A device that changes an analog signal to a digital signal of corresponding magnitude. Typically, an ADC converts a voltage to a digital number. The digital-to-analog (DAC) converter performs the reverse operation.
Application Programming Interface (API)	A series of software routines that comprise an interface between a computer application and lower level services and functions (for example, user modules and libraries). APIs serve as building blocks for programmers that create software applications.
asynchronous	A signal whose data is acknowledged or acted upon immediately, irrespective of any clock signal.
bandgap reference	A stable voltage reference design that matches the positive temperature coefficient of V_T with the negative temperature coefficient of V_{BE} , to produce a zero temperature coefficient (ideally) reference.
bandwidth	<ol style="list-style-type: none"> 1. The frequency range of a message or information processing system measured in hertz. 2. The width of the spectral region over which an amplifier (or absorber) has substantial gain (or loss); it is sometimes represented more specifically as, for example, full width at half maximum.

Glossary (continued)

microcontroller	An integrated circuit chip that is designed primarily for control systems and products. In addition to a CPU, a microcontroller typically includes memory, timing circuits, and IO circuitry. The reason for this is to permit the realization of a controller with a minimal quantity of chips, thus achieving maximal possible miniaturization. This in turn, reduces the volume and the cost of the controller. The microcontroller is normally not used for general-purpose computation as is a microprocessor.
mixed-signal	The reference to a circuit containing both analog and digital techniques and components.
modulator	A device that imposes a signal on a carrier.
noise	<ol style="list-style-type: none"> 1. A disturbance that affects a signal and that may distort the information carried by the signal. 2. The random variations of one or more characteristics of any entity such as voltage, current, or data.
oscillator	A circuit that may be crystal controlled and is used to generate a clock frequency.
parity	A technique for testing transmitting data. Typically, a binary digit is added to the data to make the sum of all the digits of the binary data either always even (even parity) or always odd (odd parity).
phase-locked loop (PLL)	An electronic circuit that controls an <i>oscillator</i> so that it maintains a constant phase angle relative to a reference signal.
pinouts	The pin number assignment: the relation between the logical inputs and outputs of the PSoC device and their physical counterparts in the printed circuit board (PCB) package. Pinouts involve pin numbers as a link between schematic and PCB design (both being computer generated files) and may also involve pin names.
port	A group of pins, usually eight.
power-on reset (POR)	A circuit that forces the PSoC device to reset when the voltage is below a pre-set level. This is one type of hardware reset.
PSoC®	Cypress Semiconductor's PSoC® is a registered trademark and Programmable System-on-Chip™ is a trademark of Cypress.
PSoC Designer™	The software for Cypress' Programmable System-on-Chip technology.
pulse-width modulator (PWM)	An output in the form of duty cycle which varies as a function of the applied measurand
RAM	An acronym for random access memory. A data-storage device from which data can be read out and new data can be written in.
register	A storage device with a specific capacity, such as a bit or byte.
reset	A means of bringing a system back to a know state. See hardware reset and software reset.
ROM	An acronym for read only memory. A data-storage device from which data can be read out, but new data cannot be written in.
serial	<ol style="list-style-type: none"> 1. Pertaining to a process in which all events occur one after the other. 2. Pertaining to the sequential or consecutive occurrence of two or more related activities in a single device or channel.
settling time	The time it takes for an output signal or value to stabilize after the input has changed from one value to another.

Glossary *(continued)*

shift register	A memory storage device that sequentially shifts a word either left or right to output a stream of serial data.
slave device	A device that allows another device to control the timing for data exchanges between two devices. Or when devices are cascaded in width, the slave device is the one that allows another device to control the timing of data exchanges between the cascaded devices and an external interface. The controlling device is called the master device.
SRAM	An acronym for static random access memory. A memory device allowing users to store and retrieve data at a high rate of speed. The term static is used because, after a value has been loaded into an SRAM cell, it remains unchanged until it is explicitly altered or until power is removed from the device.
SROM	An acronym for supervisory read only memory. The SROM holds code that is used to boot the device, calibrate circuitry, and perform Flash operations. The functions of the SROM may be accessed in normal user code, operating from Flash.
stop bit	A signal following a character or block that prepares the receiving device to receive the next character or block.
synchronous	<ol style="list-style-type: none"> 1. A signal whose data is not acknowledged or acted upon until the next active edge of a clock signal. 2. A system whose operation is synchronized by a clock signal.
tri-state	A function whose output can adopt three states: 0, 1, and Z (high-impedance). The function does not drive any value in the Z state and, in many respects, may be considered to be disconnected from the rest of the circuit, allowing another output to drive the same net.
UART	A UART or universal asynchronous receiver-transmitter translates between parallel bits of data and serial bits.
user modules	Pre-build, pre-tested hardware/firmware peripheral functions that take care of managing and configuring the lower level Analog and Digital PSoC Blocks. User Modules also provide high level <i>API</i> for the peripheral function.
user space	The bank 0 space of the register map. The registers in this bank are more likely to be modified during normal program execution and not just during initialization. Registers in bank 1 are most likely to be modified only during the initialization phase of the program.
V _{DD}	A name for a power net meaning "voltage drain." The most positive power supply signal. Usually 5 V or 3.3 V.
V _{SS}	A name for a power net meaning "voltage source." The most negative power supply signal.
watchdog timer	A timer that must be serviced periodically. If it is not serviced, the CPU resets after a specified period of time.

Document History Page *(continued)*

Description Title: CY7C603xx, enCoRe™ III Low Voltage Document Number: 38-16018				
*N	3285017	DIVA	07/07/2011	Updated Getting Started , Development Tools , and Designing with PSoC Designer . Updated Thermal Impedances and Solder Reflow Peak Temperature table.
*O	3521530	CSAI	02/10/2012	No technical updates.
*P	4623515	SIRK	01/14/2015	Updated Packaging Information : spec 51-85079 – Changed revision from *E to *F. spec 001-30999 – Changed revision from *C to *D. Updated to new template. Completing Sunset Review.

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